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(54) **HEAT DISSIPATION MODULE AND
ELECTRONIC DEVICE**

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ABSTRACT

The invention provides a heat dissipation module and an electronic device. The heat dissipation module includes a thermally conductive plastic member and a metal member. The thermally conductive plastic member includes a base and a plurality of heat dissipation fins. The base includes an upper surface and a lower surface opposite to each other, and the heat dissipation fins are arranged at intervals at the upper surface. The metal member is disposed at the lower surface of the base. The thermally conductive plastic member and the metal member are combined via insert molding. One of the thermally conductive plastic member and the metal member includes a plurality of heat dissipation bosses separated from each other, and the heat dissipation bosses are located at the lower surface of the base of the thermally conductive plastic member or at a surface of the metal member relatively far away from the base.

